SIM Lab Report Work Order - Placeholder Number

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1 Work Order Details

Work Order No	Placeholder Number
Work Order Raised By	Placeholder Name
Work Order Raised On	07 Jul 24
Sample Received Date	07 Jul 24
SIM Card Manufacturer	Placeholder Manufacturer
Testing Period	10th Sep 2020 - 15th Sep 2020
Testing Method	Stress Testing
Test Result(s)	Please refer to next pages(s)

1.1 Test Requested

In this work order Airtel SIM Lab is intending to perform the complete Offline and Online testing on above mentioned BATCH Cards received from Haryana circle.

1.2 Test Case Selection

Following test cases were selected based on the test requested.

- Vital Testing
- Physical Testing
- Profile Conformance Against Latest Profile
- Constant Voltage Stress Testing
- Voltage Testing on Class A, B & C
- Online Testing on Multiple Handsets
- DSTK Testing
- OTA Testing

1.3 SIM Details

ICCIDs	Permanent IMSI	MSISDN
8991000092210000000F	405561025717506	919954602402
8991000092210025682F	405561025719197	919957850567
8991000092210053136F	405561021510175	919954860761
8991000092210079704F	405561025721002	919954652582

2 Testing

2.1 Vital Testing

- 1.Tested look and feel of the cards received and found cards are ok.
- 2. Checked file system of the cards received and found files accessible.

2.2 Physical Testing

2.2.1 Test Procedure

In physical testing we examine the physical features and appearance of the SIM cards as per standards. There are two test cases in physical testing.

Machine ID: 2021118 Go-no-Go Gauge [3FF & 4FF] Testing (Slip Gauge)						
Sr. No.	ICCID	Specification (0.10 mm allowed on embossed cards included in max values allowed)	Observed Values (Chip Down)	Remarks (OK/NOT OK)		
1	8991000922100000 006F	0.68 mm to 0.84 mm	0.71 mm	OK		
2	8991000922100265 682F	0.68 mm to 0.84 mm	0.70 mm	OK		
3	8991000922100531 364F	0.68 mm to 0.84 mm	0.69 mm	OK		
4	8991000922100797 049F	0.68 mm to 0.84 mm	0.70 mm	OK		

2 Testing

Placeholder for Testing Section

2.1 Vital Testing

Placeholder for Vital Testing Section

2.2 Physical Testing

Placeholder for Physical Testing Section

2.2.1 Test Procedure

Placeholder for Test Procedure Section

2.2.2 Card Thickness Testing

Placeholder for Card Thickness Testing Section

2.2.3 Go-No-Go (3FF & 4FF) Testing

Placeholder for Go-No-Go (3FF & 4FF) Testing Section

2.3 Constant Voltage Stress Testing

Placeholder for Constant Voltage Stress Testing Section

2.3.1 Applications & Necessary DF on the Card

Placeholder for Applications & Necessary DF on the Card Section

2.3.2 Test Procedure

Placeholder for Test Procedure Section

2.3.3 Action Performed on SIM

Placeholder for Action Performed on SIM Section

2.3.4 Card State After Action Performed

Placeholder for Card State After Action Performed Section

2.4 Voltage Testing on Class A B and C $\,$

Placeholder for Voltage Testing on Class A B and C Section

2.4.1 Test Procedure

Placeholder for Test Procedure Section

2.4.2 Testing Details

Placeholder for Testing Details Section

2.5 Profile Conformance against latest STANDARD Profile

Placeholder for Profile	Conformance	against latest	STANDARD	Profile	Section
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2.5.1 Test Procedure

Placeholder for Test Procedure Section

2.6 Network Latching Sequence

Placeholder for Network Latching Sequence Section

2.7 DSA Testing

Placeholder for DSA Testing Section

2.7.1 Testing Details

Placeholder for Testing Details Section

2.8 Online Testing in Real Case Scenario

Placeholder for Online Testing in Real Case Scenario Section

2.8.1 Testing Details

Placeholder for Testing Details Section

2.9 DSTK Testing

Placeholder for DSTK Testing Section

2.9.1 Test Procedure

Placeholder for Test Procedure Section

2.9.2 Applications & Necessary DF on the Card

Placeholder for Applications & Necessary DF on the Card Section

2.9.3 Action Performed on SIM

Placeholder for Action Performed on SIM Section

2.9.4 Card State After Action Performed

Placeholder for Card State After Action Performed Section